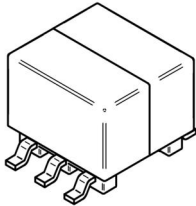
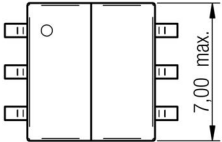
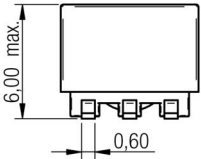
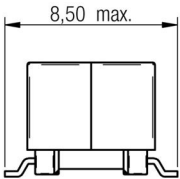
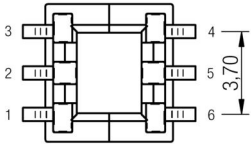
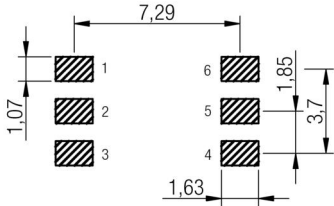


A Dimensions: [mm]



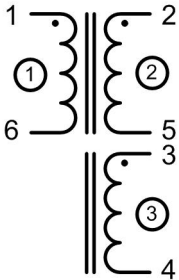
Scale - 3:1

B Recommended land pattern: [mm]



Scale - 3:1

C Schematic:



D Electrical Properties:

Properties	Test conditions		Value	Unit	Tol.
Inductance	10 kHz/ 100 mV	L	350	μH	min.
Leakage inductance	100 kHz/ 100 mV	L _S	2.3	μH	max.
DC Resistance 1		R _{DC}	700	mΩ	max.
DC Resistance 2		R _{DC}	170	mΩ	max.
DC Resistance 3		R _{DC}	170	mΩ	max.
Turns ratio		n	2.5:1:1		
Voltage-μSecond	B = 280 mT	∫ Udt	29.4	μVs	typ.
Interwinding capacitance	100 kHz/ 100 mV	C _{WW}	7	pF	typ.
Rated voltage		U _R	80	V (DC)	
Insulation test voltage		U _T	1500	V (DC)	

E General information:

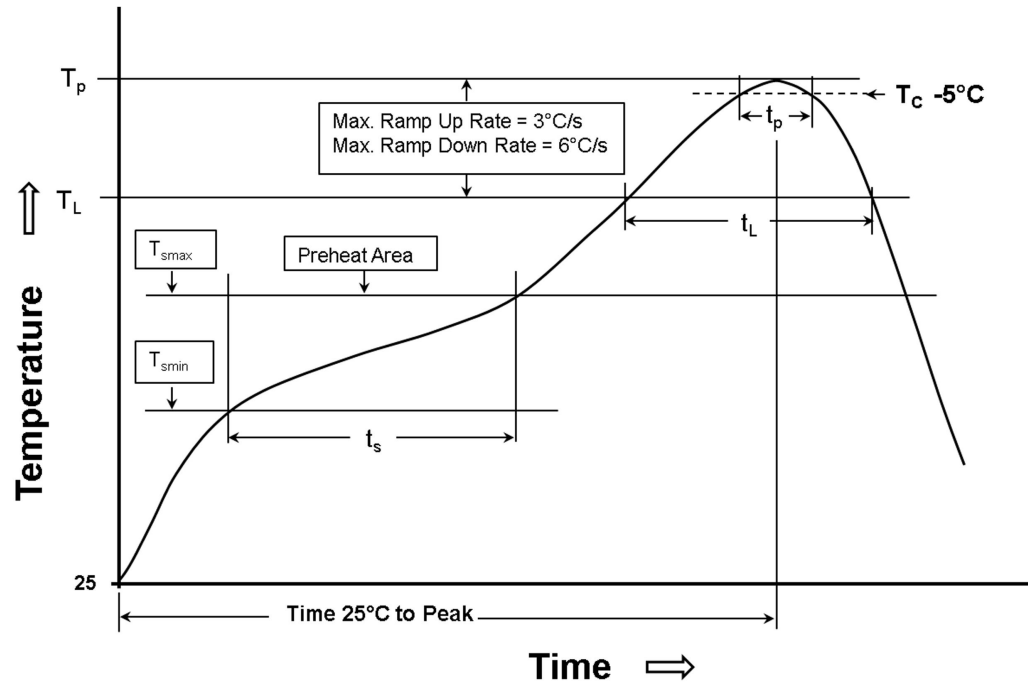
It is recommended that the temperature of the part does not exceed +125°C under worst case conditions.

- Storage Temperature: -20°C to 60°C
- Operating Temperature: -40°C to 125°C
- Test conditions of Electrical Properties: 20°C, 33% RH if not specified differently

H Soldering Specifications:



H1: Classification Reflow Profile for SMT components:



H2: Classification Reflow Profiles

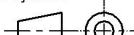
Profile Feature	Pb-Free Assembly
Preheat - Temperature Min (T_{smin}) - Temperature Max (T_{smax}) - Time (t_s) from (T_{smin} to T_{smax})	150°C 200°C 60-120 seconds
Ramp-up rate (T_L to T_P)	3°C/ second max.
Liquidous temperature (T_L) Time (t_L) maintained above T_L	217°C 60-150 seconds
Peak package body temperature (T_P)	See Table H3
Time within 5°C of actual peak temperature (t_P)	20-30 seconds
Ramp-down rate (T_P to T_L)	6°C/ second max.
Time 25°C to peak temperature	8 minutes max.

refer to IPC/JEDEC J-STD-020D

H3: Package Classification Reflow Temperature

	Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
PB-Free Assembly	< 1.6 mm	260°C	260°C	260°C
PB-Free Assembly	1.6 - 2.5 mm	260°C	250°C	245°C
PB-Free Assembly	≥ 2.5 mm	250°C	245°C	245°C

refer to IPC/JEDEC J-STD-020D

				Projection 		DESCRIPTION	WE-GDT Gate-Drive-Transformer		
1.6	2014-04-01	SSt	SSt						
1.5	2013-04-29	SSt	SSt	Würth Elektronik eiSos GmbH & Co. KG EMC & Inductive Solutions Max-Eyth-Str. 1 74638 Waldenburg Germany Tel. +49 (0) 79 42 945 - 0 www.we-online.com eiSos@we-online.com		Order. - No.	 COMPLIANT RoHS&REACH WÜRTH ELEKTRONIK	SIZE	
1.4	2012-12-10	SSt	SSt						
1.3	2012-10-29	SSt	WW						
1.2	2012-10-16	SSt	WW						
1.1	2012-06-28	SSt	SSt						
1.0	2012-04-01	SSt	WW						
REV	DATE	BY	CHECKED			Size: EP5			A4

I Cautions and Warnings:

The following conditions apply to all goods within the product series of **WE-GDT** of Würth Elektronik eiSos GmbH & Co. KG:

General:

All recommendations according to the general technical specifications of the data sheet have to be complied with.

The usage and operation of the product within ambient conditions, which probably alloy or harm the wire isolation, has to be avoided.

If the product is potted in customer applications, the potting material might shrink during and after hardening. The product is exposed to the pressure of the potting material with the effect that the core, wire and termination is possibly damaged by this pressure and so the electrical as well as the mechanical characteristics are endangered to be affected. After the potting material is cured, the core, wire and termination of the product have to be checked if any reduced electrical or mechanical functions or destructions have occurred.

The responsibility for the applicability of customer specific products and use in a particular customer design is always within the authority of the customer. All technical specifications for standard products do also apply to customer specific products.

Cleaning agents that are used to clean the customer application might damage or change the characteristics of the component, body, pins or termination.

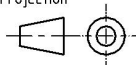
Direct mechanical impact to the product shall be prevented as the ferrite material of the core could flake or in the worst case it could break.

Product specific:

Follow all instructions mentioned in the data sheet, especially:

- The soldering profile has to be complied with according to the technical reflow soldering specification, otherwise this will void the warranty.
- Wave soldering is not applicable. Reflow soldering is recommended.
- All products shall be used before the end of the period of 12 months based on the product date code, if not a 100% solderability can't be ensured.
- Violation of the technical product specifications such as exceeding the nominal rated current will void the warranty.



				Projection 		DESCRIPTION		
1.6	2014-04-01	SSt	SSt			WE-GDT Gate-Drive-Transformer		
1.5	2013-04-29	SSt	SSt					
1.4	2012-12-10	SSt	SSt	Würth Elektronik eiSos GmbH & Co. KG EMC & Inductive Solutions Max-Eyth-Str. 1 74638 Waldenburg Germany Tel. +49 (0) 79 42 945 - 0 www.we-online.com eiSos@we-online.com		Order.- No.		SIZE
1.3	2012-10-29	SSt	WW			760301103		
1.2	2012-10-16	SSt	WW				Size: EP5	
1.1	2012-06-28	SSt	SSt					
1.0	2012-04-01	SSt	WW					
REV	DATE	BY	CHECKED					

This electronic component has been designed and developed for usage in general electronic equipment only. This product is not authorized for use in equipment where a higher safety standard and reliability standard is especially required or where a failure of the product is reasonably expected to cause severe personal injury or death, unless the parties have executed an agreement specifically governing such use. Moreover Würth Elektronik eiSos GmbH & Co KG products are neither designed nor intended for use in areas such as military, aerospace, aviation, nuclear control, submarine, transportation (automotive control, train control, ship control), transportation signal, disaster prevention, medical, public information network etc.. Würth Elektronik eiSos GmbH & Co KG must be informed about the intent of such usage before the design-in stage. In addition, sufficient reliability evaluation checks for safety must be performed on every electronic component which is used in electrical circuits that require high safety and reliability functions or performance.

